AN ELECTRONIC DEVICE PACKAGE AND METHOD OF MANUFACTURE

ABSTRACT OF THE DISCLOSURE

A method of manufacturing an electronic device package. Coating a first side of a metallic layer with a first insulating layer and coating a second opposite side of the metallic layer with a second insulating layer. Patterning the first insulating layer to expose bonding locations on the first side of the metallic layer, and patterning the second insulating layer such that remaining portions of the second insulating layer on the second opposite side are located directly opposite to the bonding locations on the first side. Selectively removing portions of the metallic layer that are not covered by the remaining portions of the second insulating layer on the second opposite side to form separated coplanar metallic layers. The separated coplanar metallic layers include the bonding locations. Selectively removing remaining portions of the second insulating layer thereby exposing second bonding locations on the second opposite sides of the separated coplanar metallic layers.